

SILICON GATE CMOS

PRELIMINARY

262,144 WORD x 16 BIT STATIC RAM

Description

The TC554161FTL/TRL is a 4,194,304 bit CMOS static random access memory organized as 262,144 words by 16 bits and operated from a single 5V power supply. Advanced circuit techniques provide both high speed and low power features with an operating current of 10mA/MHz (typ.) and a minimum cycle time of 70ns. When \overline{CE} is a logical high, the device is placed in a low power standby mode in which the standby current is 100 μ A (max.). The TC554161FTL/TRL has two control inputs. A chip enable input (\overline{CE}) allows for device selection and data retention control, while an output enable input (\overline{OE}) provides fast memory access. Byte access is supported by upper and lower byte controls. The TC554161FTL/TRL is suitable for use in microprocessor systems where high speed, low power, and battery backup are required. The TC554161FTL/TRL is offered in a 54-pin thin small outline plastic package (forward type, reverse type).

Features

- Low power dissipation: 55mW/MHz (typ.)
- Standby current: 100 μ A (max.)
- Single 5V power supply
- Access time (max.)

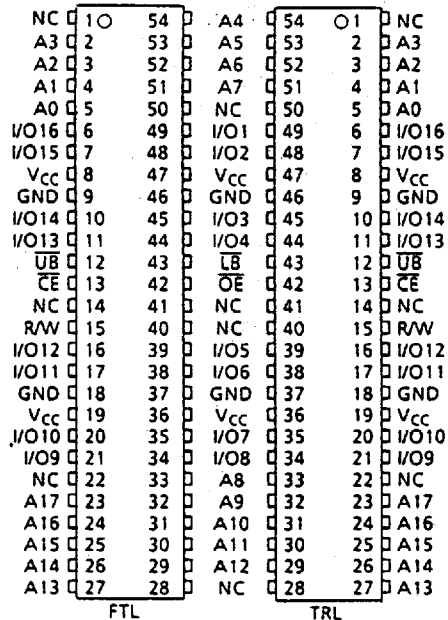
	TC554161FTL/TRL		
	-70	-85	-10
Access Time	70ns	85ns	100ns
\overline{CE} Access Time	70ns	85ns	100ns
\overline{OE} Access Time	35ns	45ns	50ns

- Power down feature: \overline{CE}
- Data retention supply voltage: 2.0 ~ 5.5V
- Inputs and outputs TTL compatible
- Package TC554161FTL : TSOP54-P-400
TC554161TRL : TSOP54-P-400A

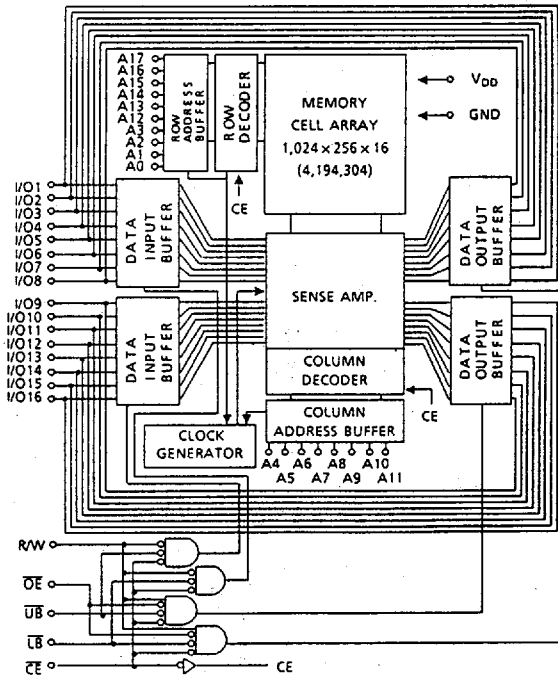
Pin Names

A0 ~ A17	Address Inputs
I/O1 ~ I/O16	Data Input/Output
\overline{CE}	Chip Enable Input
R/W	Read/Write Control Input
\overline{OE}	Output Enable Input
\overline{LB} , \overline{UB}	Data Byte Control Input
V_{DD}	Power (+5V)
GND	Ground
NC	No Connection

Pin Connection (Top View)



Block Diagram



Operating Mode

MODE \ PIN	CE	OE	R/W	LB	UB	I/O1 ~ I/O8	I/O9 ~ I/O16	POWER
Read	L	L	H	L	L	Output	Output	I _{DD0}
				H	L	High Impedance	Output	I _{DD0}
Write	L	*	L	L	H	Output	High Impedance	I _{DD0}
				H	L	Input	Input	I _{DD0}
Output Deselect	L	H	H	*	*	High Impedance	High Impedance	I _{DD0}
				H	H	High Impedance	High Impedance	I _{DD0}
Standby	H	*	*	*	*	High Impedance	High Impedance	I _{DD5}

* H or L

Maximum Ratings

SYMBOL	ITEM	RATING	UNIT
V _{DD}	Power Supply Voltage	-0.3 ~ 7.0	V
V _{IN}	Input Voltage	-0.3* ~ 7.0	V
V _{IO}	Input and Output Voltage	-0.5* ~ V _{DD} + 0.5	V
P _D	Power Dissipation	0.6	W
T _{SOLDER}	Soldering Temperature • Time	260 • 10	°C • sec
T _{STRG}	Storage Temperature	-55 ~ 150	°C
T _{OPR}	Operating Temperature	0 ~ 70	°C

* -3.0V with a pulse width of 30ns

DC Recommended Operating Conditions

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_{DD}	Power Supply Voltage	4.5	5.0	5.5	V
V_{IH}	Input High Voltage	2.2	-	$V_{DD} + 0.3$	
V_{IL}	Input Low Voltage	-0.3*	-	0.8	
V_{DH}	Data Retention Supply Voltage	2.0	-	5.5	

* -3.0V with a pulse width of 30ns

DC Characteristics ($T_a = 0 \sim 70^\circ\text{C}$, $V_{DD} = 5V \pm 10\%$)

SYMBOL	PARAMETER	TEST CONDITION		MIN.	TYP.	MAX.	UNIT	
I_{LI}	Input Leakage Current	$V_{IN} = 0 \sim V_{DD}$		-	-	± 1.0	μA	
I_{LO}	Output Leakage Current	$\overline{CE} = V_{IH}$ or $R/W = V_{IL}$ or $\overline{OE} = V_{IH}$ $V_{OUT} = 0 \sim V_{DD}$		-	-	± 1.0	μA	
I_{OH}	Output High Current	$V_{OH} = 2.4\text{V}$		-1.0	-	-	mA	
I_{OL}	Output Low Current	$V_{OL} = 0.4\text{V}$		2.1	-	-	mA	
I_{DDO1}	Operating Current	$\overline{CE} = V_{IL}$, $I_{OUT} = 0\text{mA}$ Other Inputs = V_{IH}/V_{IL}	t_{cycle}	Min.	-	-	100	mA
				$1\mu\text{s}$	-	15	-	
I_{DDO2}		$\overline{CE} = 0.2\text{V}$, $I_{OUT} = 0\text{mA}$ Other Inputs = V_{IH}/V_{IL}	t_{cycle}	Min.	-	-	90	
				$1\mu\text{s}$	-	10	-	
I_{DDs1}	Standby Current	$\overline{CE} = V_{IH}$, Other Inputs = V_{IH}/V_{IL}		-	-	3	mA	
I_{DDs2}		$\overline{CE} = V_{DD} - 0.2\text{V}$ $V_{DD} = 2.0\text{V} \sim 5.5\text{V}$		-	-	100	μA	

Capacitance* ($T_a = 25^\circ\text{C}$, $f = 1.0\text{MHz}$)

SYMBOL	PARAMETER	TEST CONDITION	MAX.	UNIT
C_{IN}	Input Capacitance	$V_{IN} = \text{GND}$	10	pF
C_{OUT}	Output Capacitance	$V_{OUT} = \text{GND}$	10	

*This parameter is periodically sampled and is not 100% tested.

AC Characteristics (Ta = 0 ~ 70°C, V_{DD} = 5V±10%)

Read Cycle

SYMBOL	PARAMETER	TC554161FTL/TRL						UNIT
		-70		-85		-10		
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
t _{RC}	Read Cycle Time	70	—	85	—	100	—	ns
t _{ACC}	Address Access Time	—	70	—	85	—	100	
t _{CO}	\overline{CE} Access Time	—	70	—	85	—	100	
t _{OE}	\overline{OE} Access Time	—	35	—	45	—	50	
t _{BA}	$\overline{UB}, \overline{LB}$ Access Time	—	35	—	45	—	50	
t _{OH}	Output Data Hold Time from Address Change	10	—	10	—	10	—	
t _{COE}	Output Enable Time from \overline{CE}	10	—	10	—	10	—	
t _{OEE}	Output Enable Time from \overline{OE}	5	—	5	—	5	—	
t _{BE}	Output Enable Time from $\overline{UB}, \overline{LB}$	5	—	5	—	5	—	
t _{OD}	Output Disable Time from \overline{CE}	—	25	—	30	—	35	
t _{ODO}	Output Disable Time from \overline{OE}	—	25	—	30	—	35	
t _{BD}	Output Disable Time from $\overline{UB}, \overline{LB}$	—	25	—	30	—	35	

Write Cycle

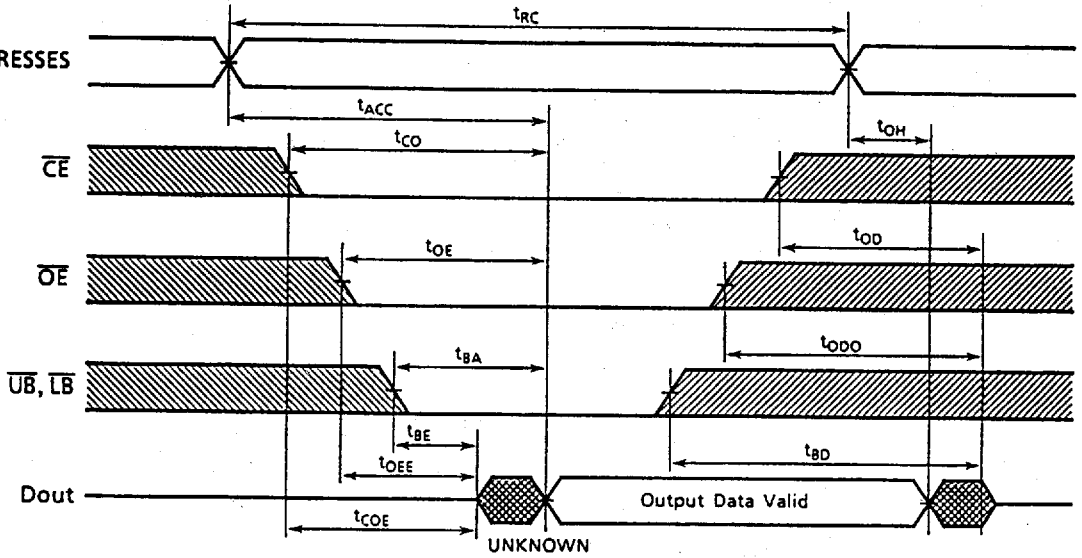
SYMBOL	PARAMETER	TC554161FTL/TRL						UNIT
		-70		-85		-10		
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
t _{WC}	Write Cycle Time	70	—	85	—	100	—	ns
t _{WP}	Write Pulse Width	50	—	55	—	60	—	
t _{CW}	Chip Enable to End of Write	60	—	70	—	80	—	
t _{BW}	$\overline{UB}, \overline{LB}$ Enable to End of Write	50	—	55	—	60	—	
t _{AS}	Address Setup Time	0	—	0	—	0	—	
t _{WR}	Write Recovery Time	0	—	0	—	0	—	
t _{DS}	Data Setup Time	30	—	35	—	40	—	
t _{DH}	Data Hold Time	0	—	0	—	0	—	
t _{OE_W}	Output Enable Time from R/W	5	—	5	—	5	—	
t _{OD_W}	Output Disable Time from R/W	—	25	—	30	—	35	

AC Test Conditions

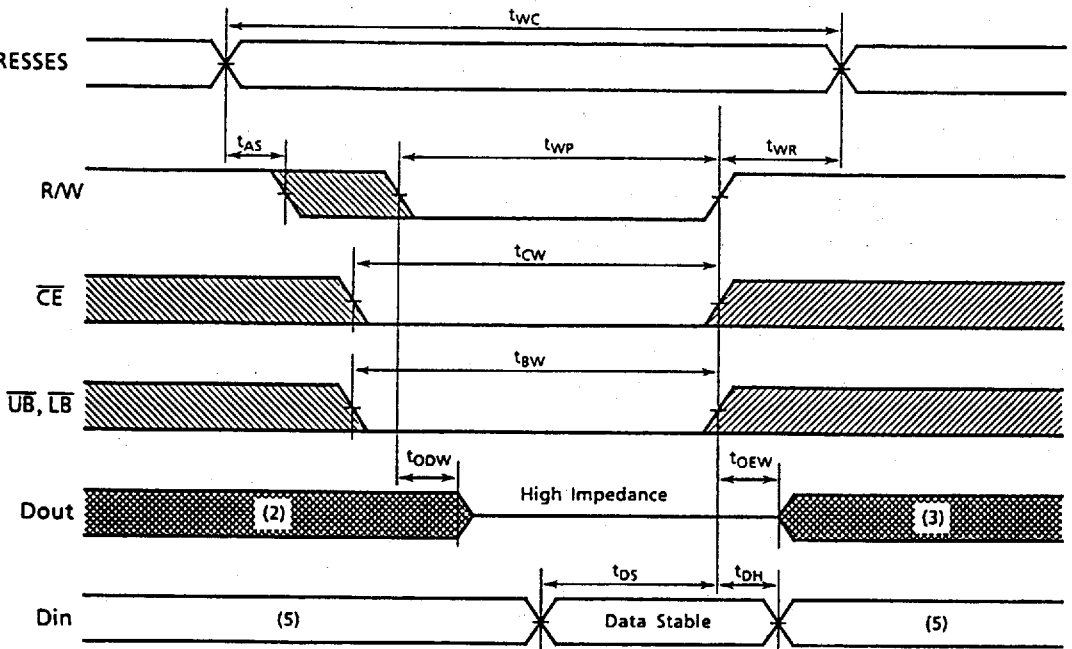
Input Pulse Levels	2.4V/0.6V
Input Pulse Rise and Fall Time	5ns
Input Timing Measurement Reference Levels	1.5V
Output Timing Measurement Reference Levels	1.5V
Output Load	1 TTL Gate and C _L = 100pF

Timing Waveforms

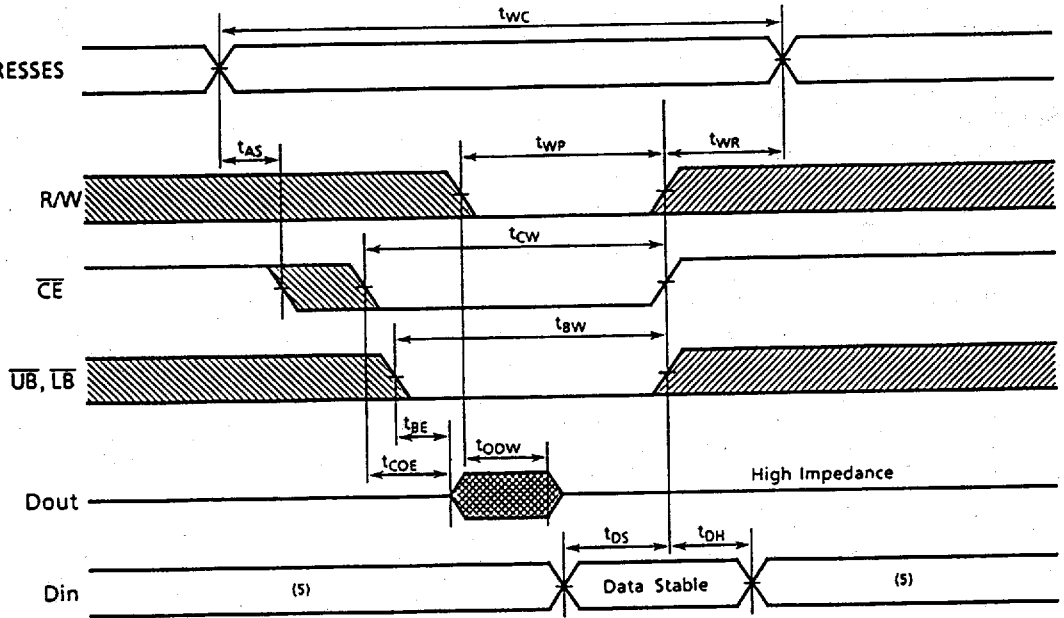
Read Cycle ⁽¹⁾



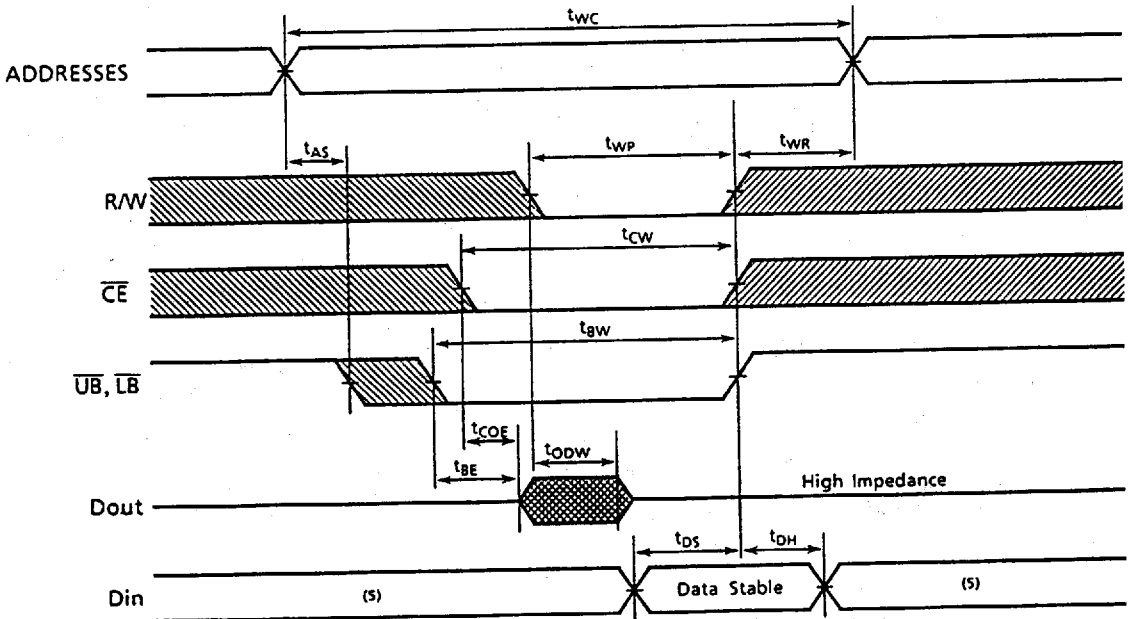
Write Cycle 1 ⁽⁴⁾ (R/W Controlled Write)



Write Cycle 2 ⁽⁴⁾ (\overline{CE} Controlled Write)



Write Cycle 3 ⁽⁴⁾ ($\overline{UB}, \overline{LB}$ Controlled Write)



Notes:

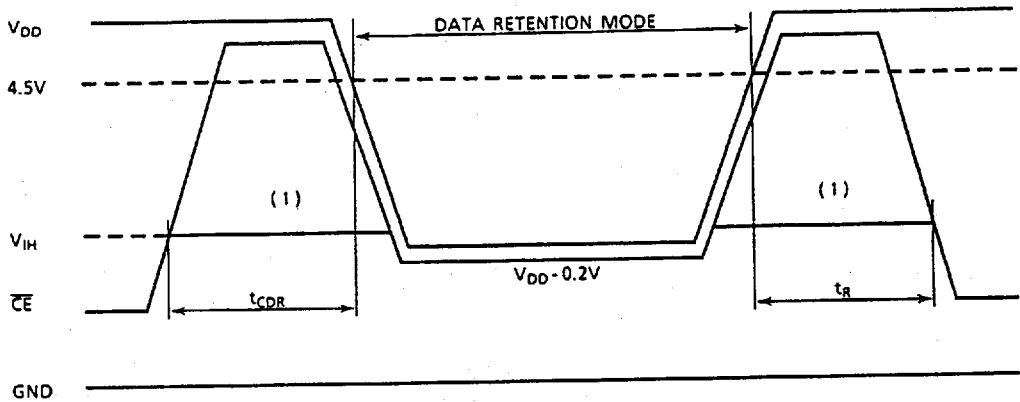
1. R/W is high for read cycles.
2. If the \overline{CE} low transition occurs coincident with or after the R/W low transition, outputs remain in a high impedance state.
3. If the \overline{CE} high transition occurs coincident with or prior to the R/W high transition, outputs remain in a high impedance state.
4. If \overline{OE} is high during a write cycle, the outputs are in a high impedance state during this period.
5. The I/O may be in the output state during this time; therefore input signals of opposite phase must not be applied.

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Data Retention Characteristics (Ta = 0 ~ 70°C)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{DH}	Data Retention Supply Voltage	2.0	-	5.5	V
I _{DDS2}	Standby Current	V _{DH} = 3.0V	-	50	μA
		V _{DH} = 5.5V	-	100	
t _{CDR}	Chip Deselect to Data Retention Mode	0	-	-	ns
t _R	Recovery Time	5	-	-	ms

\overline{CE} Controlled Data Retention Mode



Note:

1. If the V_{IH} of \overline{CE} is 2.2V in operation, during the period that the V_{DD} voltage is going down from 4.5V to 2.4V, I_{DDS1} current flows.